

**CTI $\geq$ 600V\*1  
PLC=0**

**UL FR-15.1  
RTI 150°C\*2**

**High voltage CAF  
resistance (1000V)**

\*1 Measurement by ASTM method \*2 0.63mm or more

**Applications**  
**Automotive/Industry**

On Board Charger, DC/DC Converter, Inverter,  
In-Wheel Motor.  
EV Charging Stand, HV Control Unit, PV Module.



## Halogen-free

Laminate

**R-3566D**

Prepreg

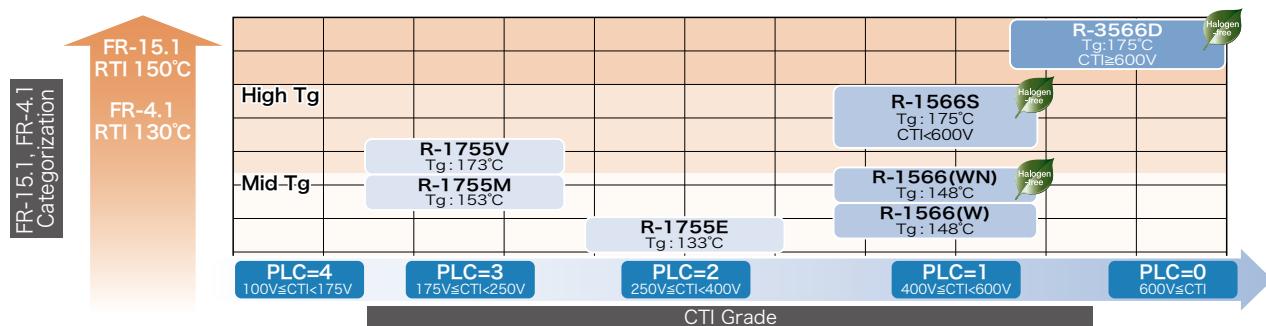
**R-3551D**

### High CTI, High RTI Halogen-free multi-layer circuit board materials

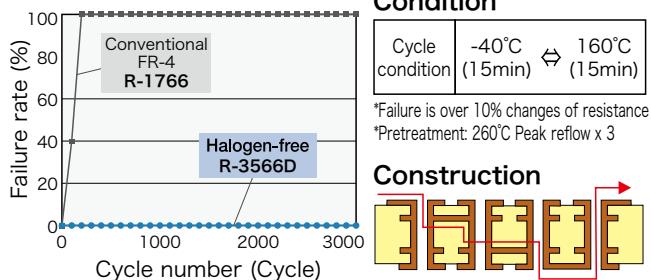
Supports high heat resistance and high withstand voltage required for xEV and industrial devices.

Support in reduction of PCB board size due to reduced creepage distances by excellent tracking resistance (PLC=0). Halogen-free material reducing environmental impact.

#### Line-up



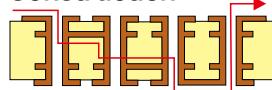
#### Through-hole reliability



#### Condition

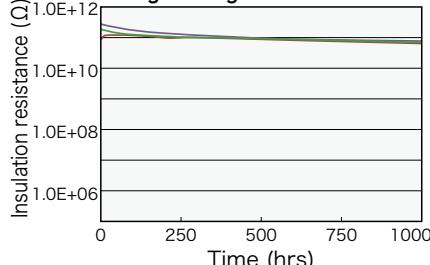
|  |   |
|--|---|
| Cycle condition                            | -40°C (15min) $\leftrightarrow$ 160°C (15min) |
| *Failure is over 10% changes of resistance |   |
| *Pretreatment: 260°C Peak reflow x 3       |   |

#### Construction



#### Insulation reliability

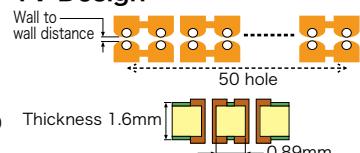
##### High voltage CAF evaluation



#### Condition

|                                    |                             |
|------------------------------------|-----------------------------|
| Pretreatment                       | 260°C Peak reflow x 3 times |
| Condition                          | 85°C, 85%RH, DC 1000V       |
| Through-hole wall to wall distance | 0.89mm                      |

#### TV Design



#### General properties

| Item                            |                     | Test method         | Condition  | Unit   | Halogen-free R-3566D | Halogen-free R-1566(W) |
|---------------------------------|---------------------|---------------------|------------|--------|----------------------|------------------------|
| Glass transition temp.(Tg)      | DSC                 | A                   | °C         |        | 175                  | 148                    |
|                                 | TMA                 |                     |            |        | 170                  | 145                    |
| Thermal decomposition temp.(Td) |                     | TGA                 | A          | °C     | 355                  | 350                    |
| T288(with copper)               |                     | IPC-TM-650 2.4.24.1 | A          | min    | 10                   | 3                      |
| CTE z-axis                      | $\alpha_1/\alpha_2$ | IPC-TM-650 2.4.24   | A          | ppm/°C | 40 / 180             | 40 / 180               |
| RTI* / PLC*                     |                     | UL                  | C-48/23/50 | -      | 150 / 0              | 130 / 1                |
| Peel strength                   | 1oz(35 μm)          | IPC-TM-650 2.4.8    | A          | kN/m   | 1.6                  | 1.8                    |
| Flammability                    |                     | UL                  | C-48/23/50 | -      | 94V-0                | 94V-0                  |

The sample thickness is 0.8mm.

\* The sample thickness is 1.6mm.

Our Halogen-free materials are based on JPCA-ES-01-2003 standard and others.

The above data are typical values and not guaranteed values.

